Claims

1. A method of plating a surface to be plated comprising premixing a plating solution with additive comprising diamond particles.

2. The method according to claim 1, wherein the plating method is electroplating.

3. The method according to claim 1, wherein the plating method is electroless-plating.

4. The method according to claim 1, wherein the additive particles comprises nano-size diamond particles.

5. The method according to claim 1, wherein the additive particles comprises micro-size diamond particles.

~~6. The method according to claim 1, wherein the additive particles is postmix comprising the diamond particles and water.~~

~~7. The method according to claim 1, wherein the diamond particles are doped and suspended in the plating solution.~~

~~8. The method according to claim 7, wherein the diamond particles are randomly distributed evenly in the plating solution.~~

~~9. The method according to claim 1, wherein the additive can be added into any plating solution.~~

~~10. The method according to claim 1, wherein the additive comprises about 0.1 ~ 5.0 wt% of diamond particles and about 95.0 ~ 99.9 wt% of the plating solution.~~

~~11. The method according to claim 1, wherein the additive comprises about 0.25 ~ 2.5 wt% of diamond particles and about 97.5 ~ 99.75 wt% of plating solution.~~

~~12. An additive for use in any one of the preceding claims.~~